



The Strip Detector of the PANDA MVD

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on behalf of the PANDA MVD Group

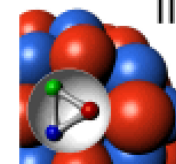
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RD13 Conference

July 5th, 2013



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Outline

1. Design of the PANDA MVD

- The PANDA Experiment
- Disk and Barrel Parts of the Detector
- Mechanical Integration of the Barrels
- Powering Concept

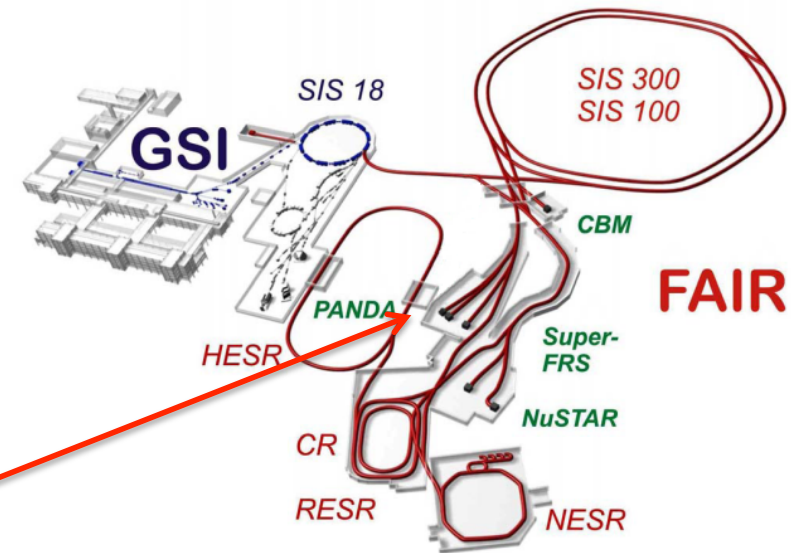
2. Hardware developments

- Front-end ASIC
- Double-sided Silicon Strip Sensors
- Sensor Irradiations
- Hybrid Bus

Design of the PANDA MVD

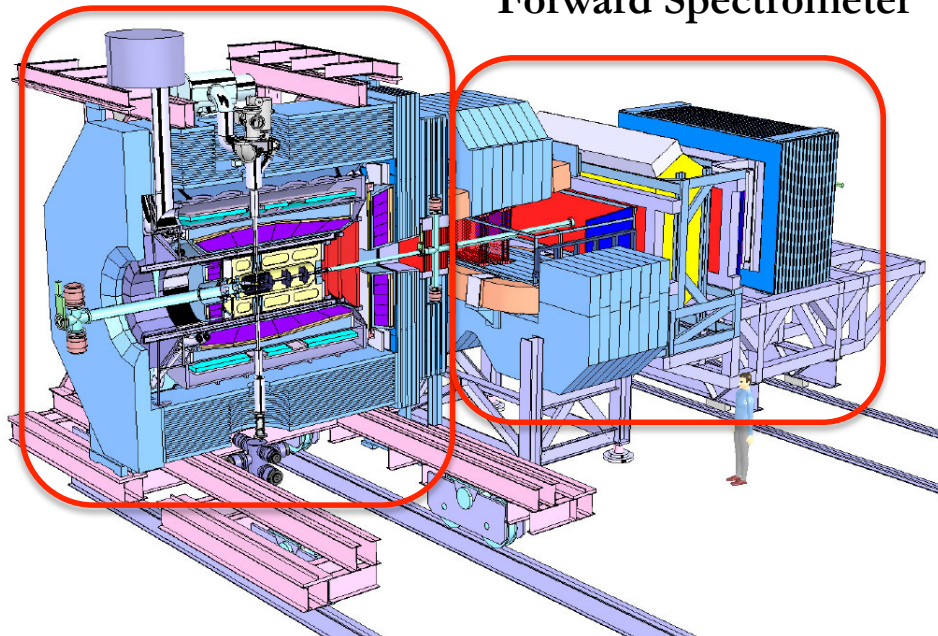
The PANDA Experiment

- Fixed target experiment at FAIR, Darmstadt
- Antiproton beam with $p = 1.5 - 15 \text{ GeV}/c$ and hydrogen or nuclear target
- Maximum luminosity $2 \cdot 10^{32} \text{ cm}^{-2} \text{ s}^{-1}$; interaction rate $2 \cdot 10^7 \text{ s}^{-1}$
- Continuous, triggerless readout



Target Spectrometer

Forward Spectrometer

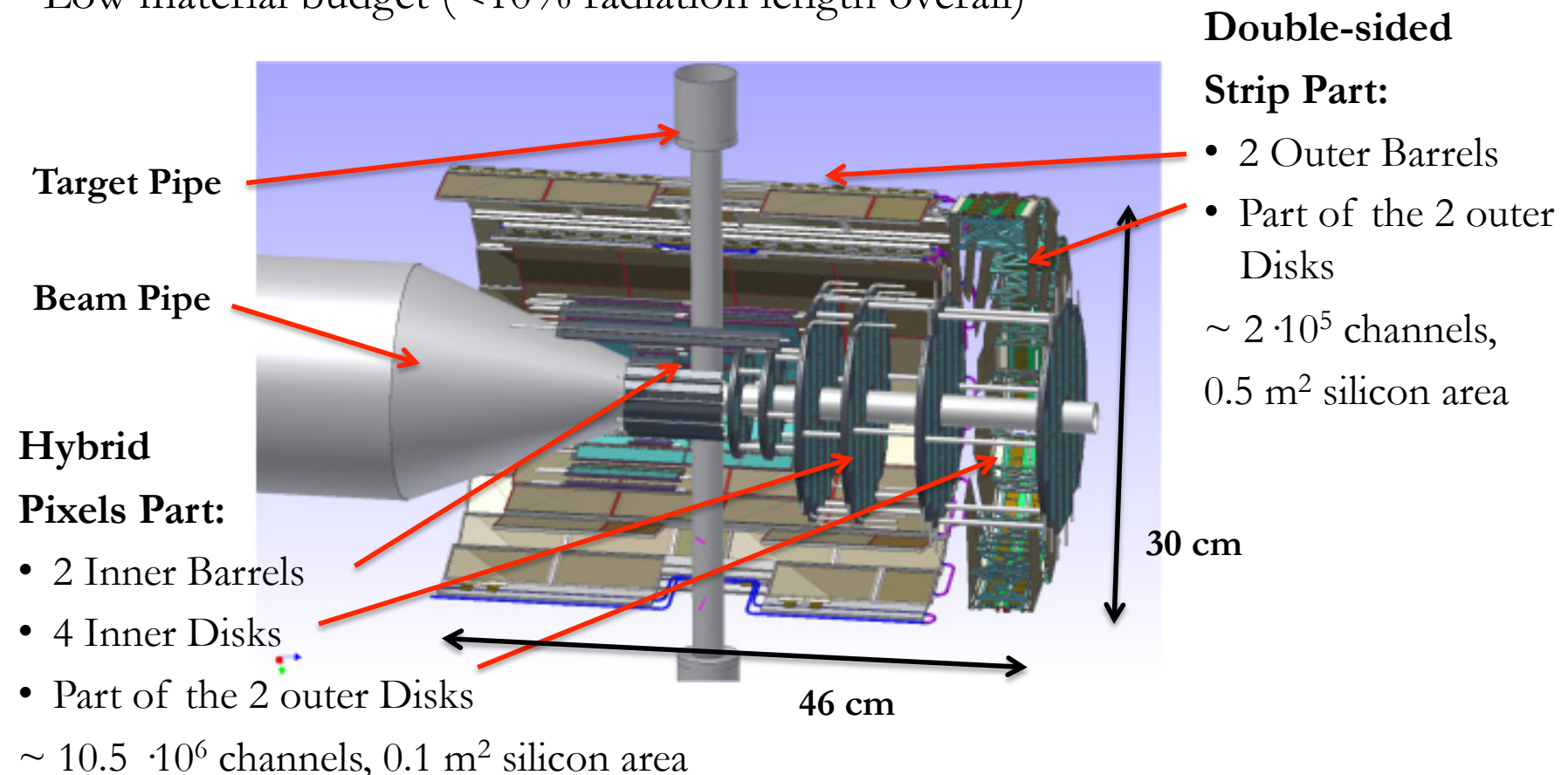


Physics program:

- High precision charmonium spectroscopy
- Search for hybrids and glueballs
- Study of exotic states (X, Y, Z)
- Nucleon structure
- Hyper-nuclear physics

The Micro Vertex Detector

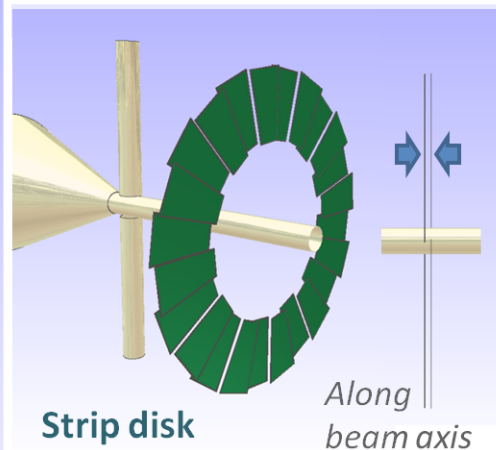
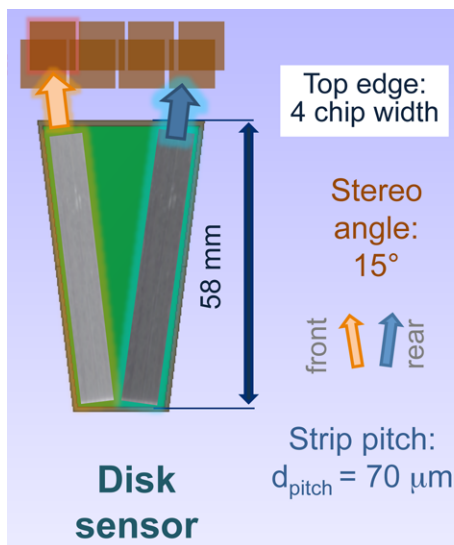
- High resolution ($<100\text{ }\mu\text{m}$) vertexing; good time resolution ($<6\text{ ns}$)
- Radiation tolerance up to $\sim 4 \cdot 10^{14}\text{ n}_{1\text{MeV eq}}/\text{cm}^2$
- High rate capability ($2 \cdot 10^7\text{ pbar-p annihilations/s}$) and triggerless readout
- Low material budget ($<10\%$ radiation length overall)



Strip Disks

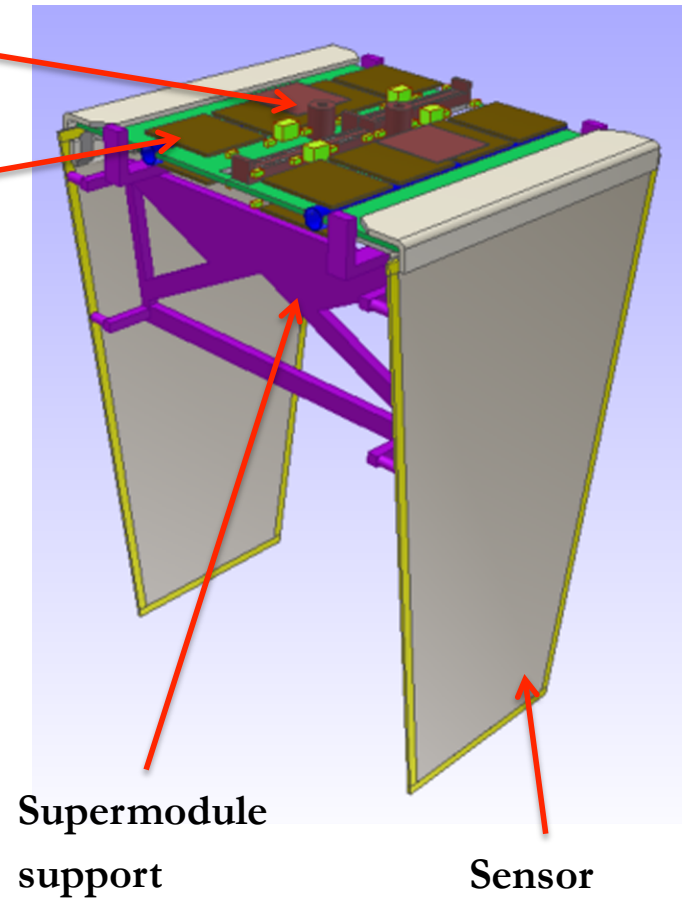
Disk part:

- Trapezoidal sensors
- Stereo angle: 15°
- Strip pitch: $67.5 \mu\text{m}$
- 512 channels per side
- Supermodule: two corresponding sensors on the two disks
- 2 disks at $z = 155$ and 215 mm , 24 sensors per disk



Module controller
ASIC

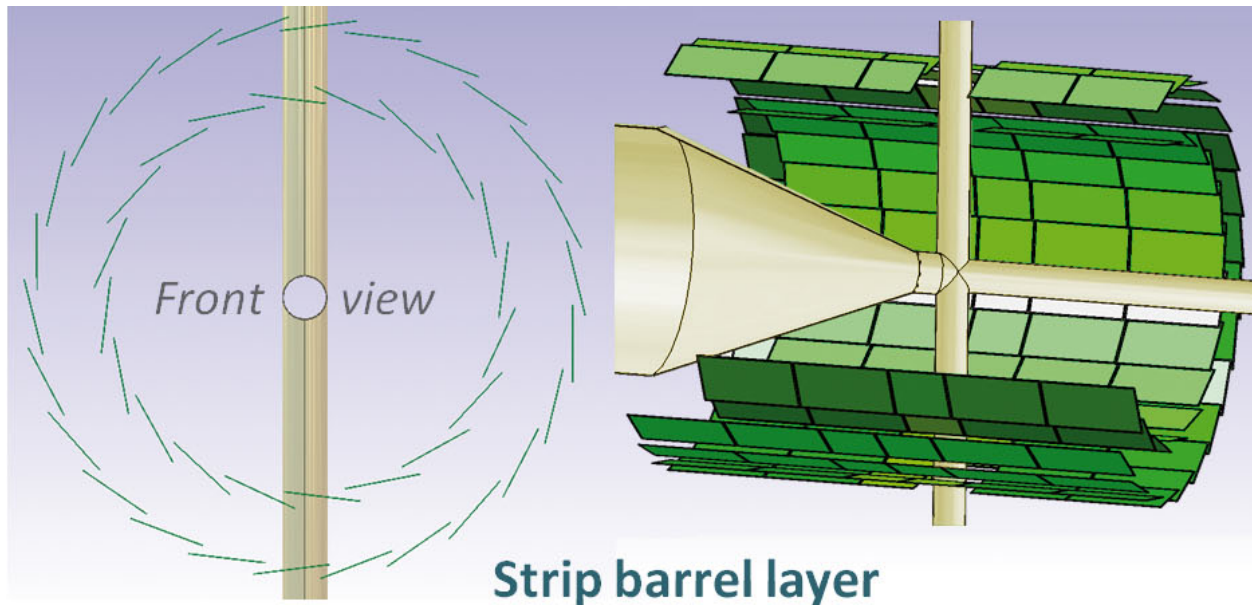
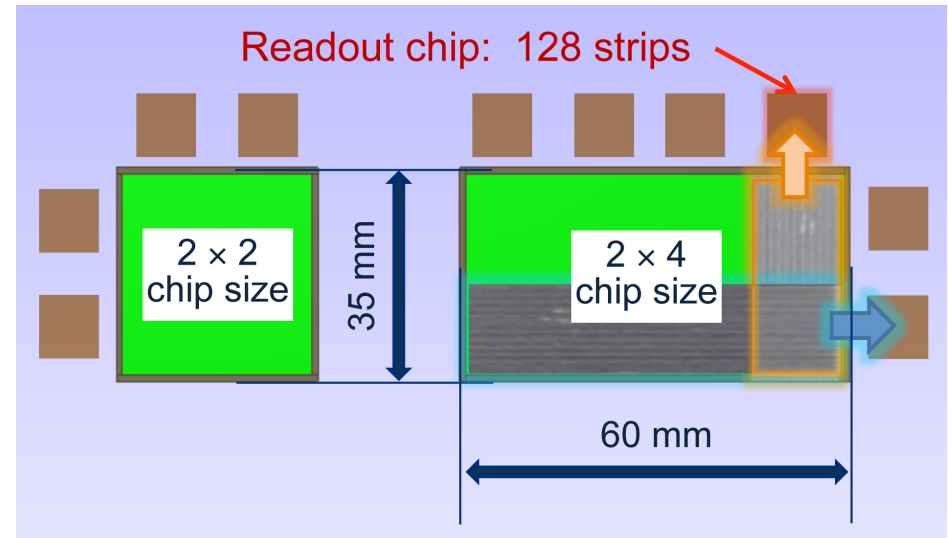
Front-end
ASIC



Strip Barrels

Barrel part:

- Rectangular (512×896 channels) and squared (512×512 channels) sensors
- Stereo angle: 90° , strip pitch $65 \mu\text{m}$
- Two barrels at $r = 92$ and 125 mm
- 4 – 6 sensors on each of the 46 staves (248 sensors in total)

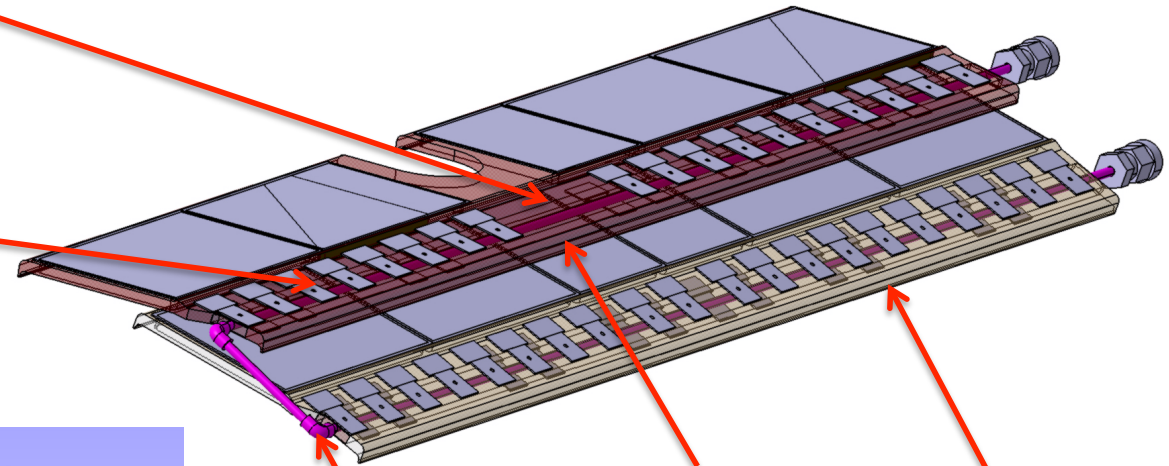


Strip Barrels – Stave Design I

Strip supermodule:

Module controller
(ASIC)

Front-end electronics
(ASIC)

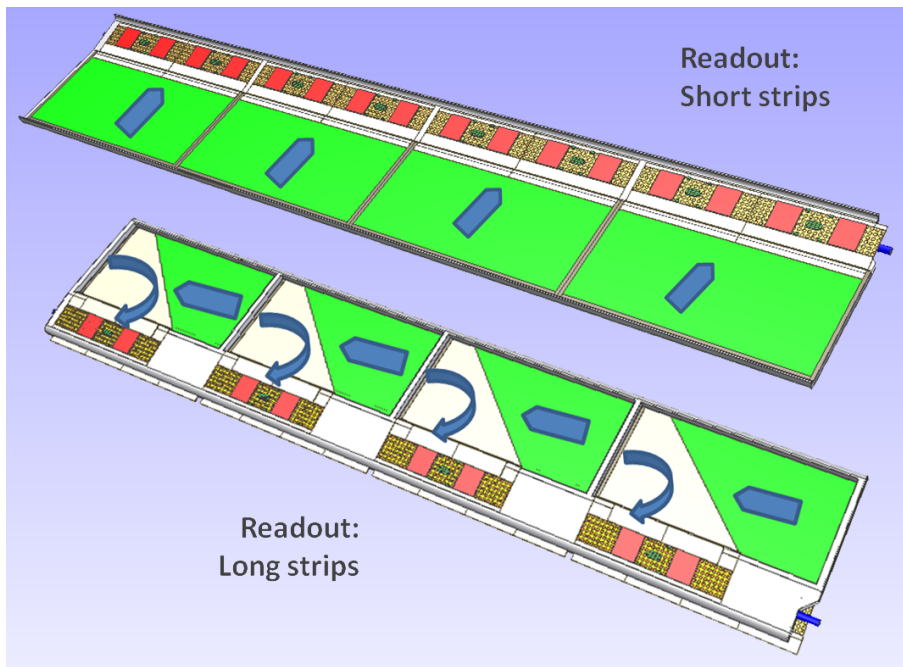


Hybrid PCB

Cooling loop between
two adjacent staves

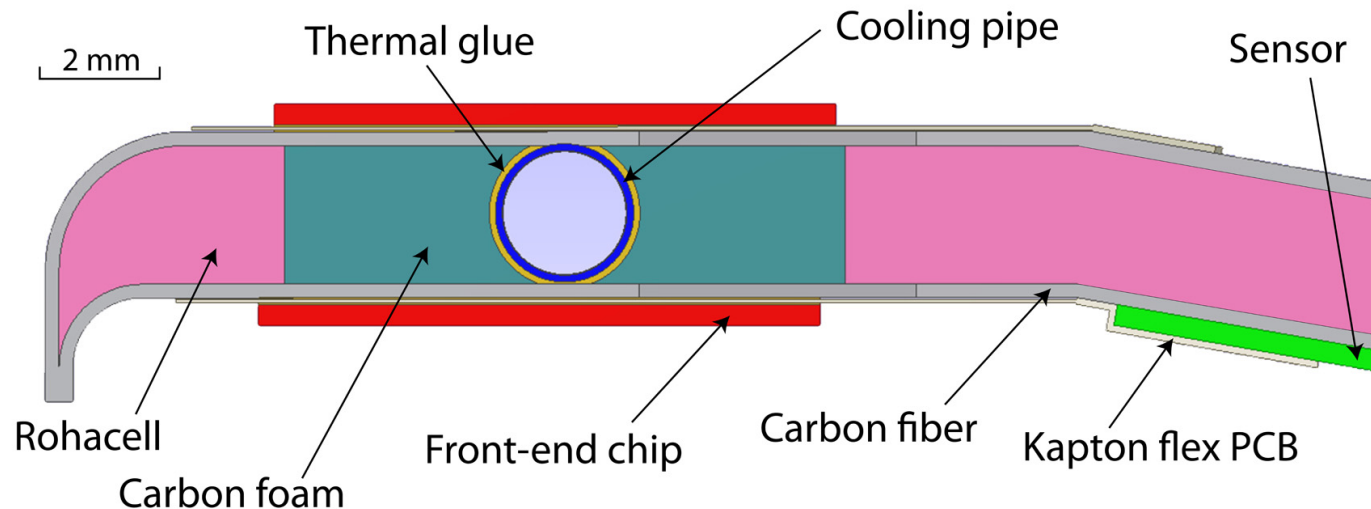
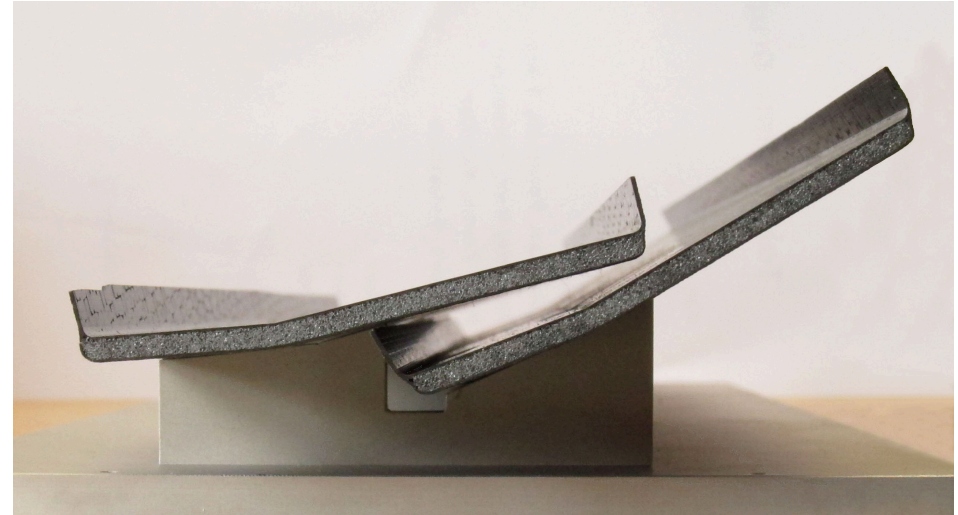
Composite
stave with
embedded
cooling pipe

Readout concept:



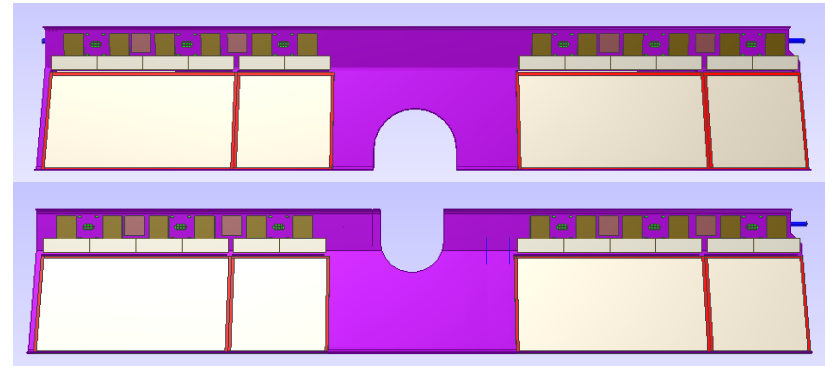
Strip Barrels – Stave Design II

- Sandwich structure of carbon fiber (200 μm) and foam (2 mm)
- Up to 18 W dissipated on one stave
→ active water cooling
- Embedded cooling pipe in nickel-cobalt alloy (2 mm diameter, 80 μm wall thickness)
- Carbon foam (POCO HTC) in the area around the cooling pipe

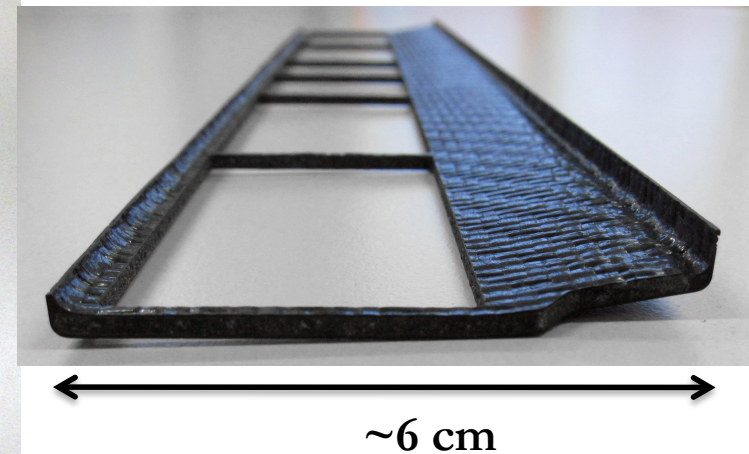
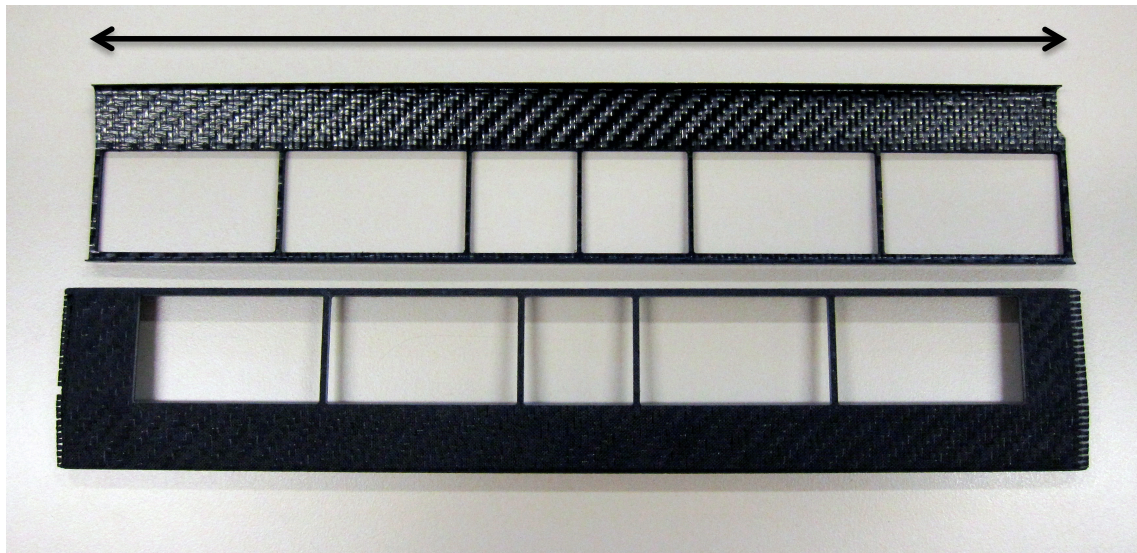


Strip Barrels – Stave Design III

- Large cutouts for the sensors
- Special design for top/bottom staves around the target pipe
- 6 different designs in total

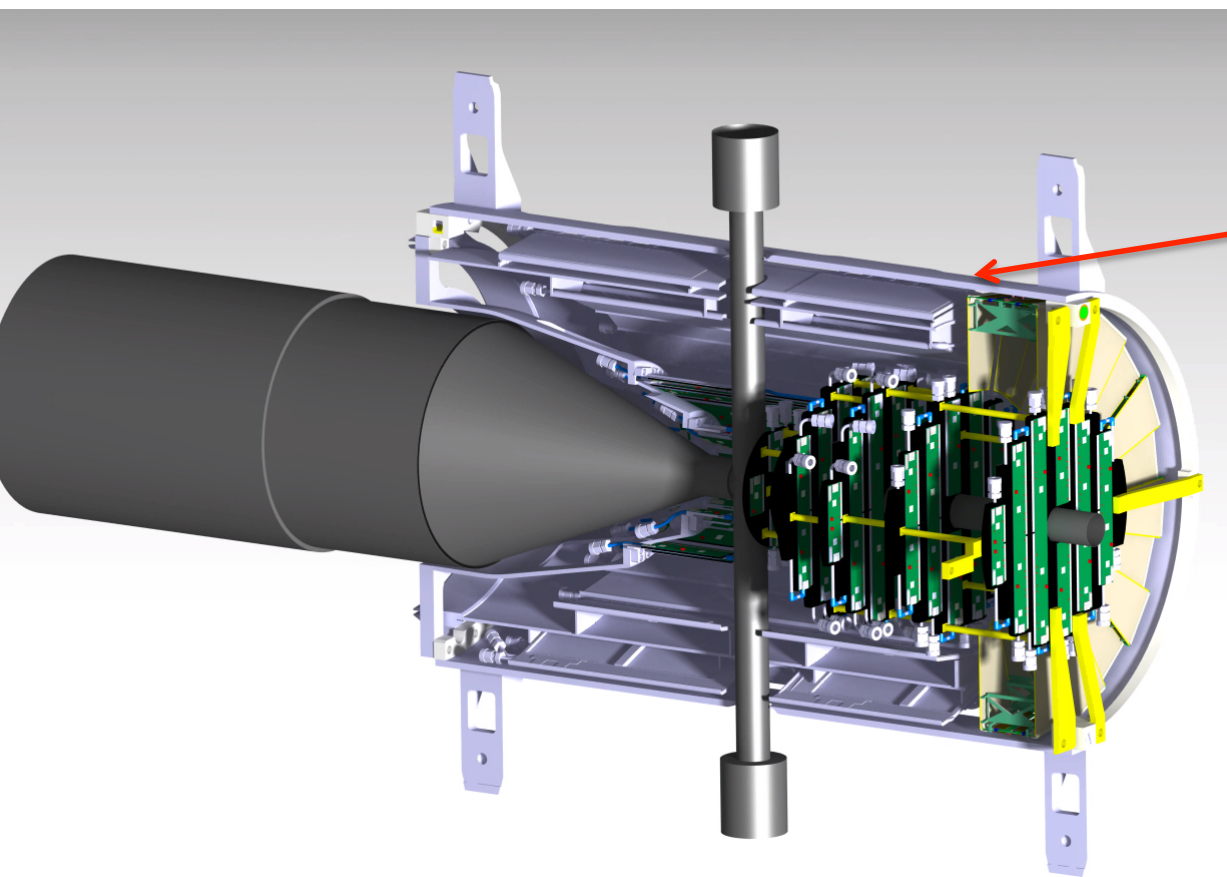


31.3 cm

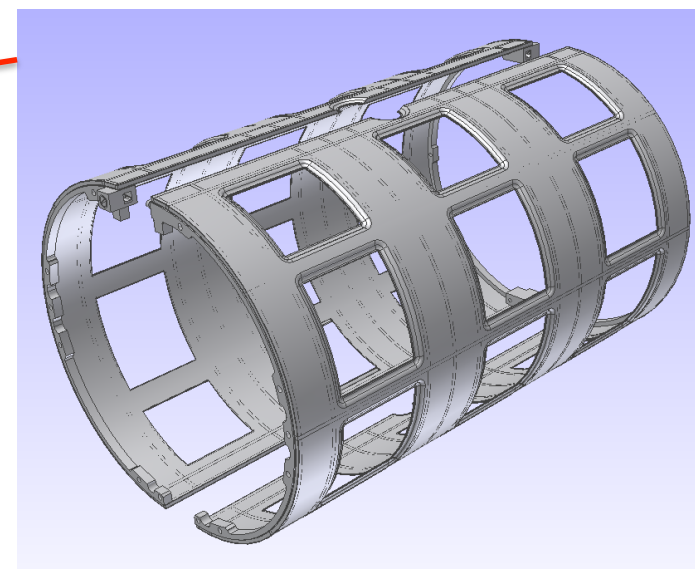


- Waiting for a prototype complete with cooling pipe to perform thermal tests

Mechanical Integration

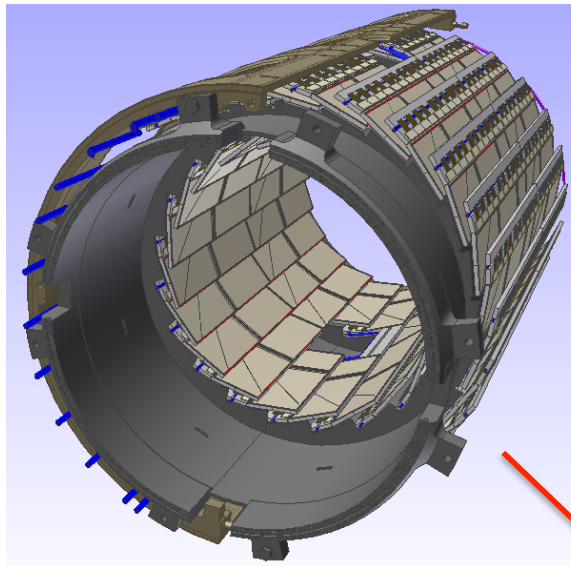


Complete half-detector

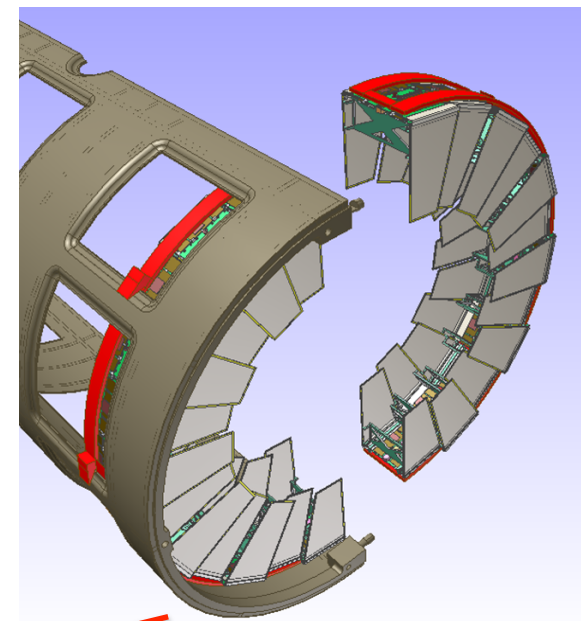
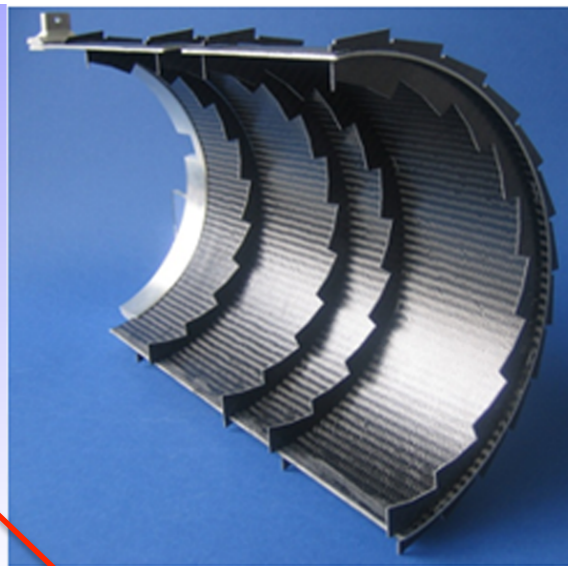


Global frame

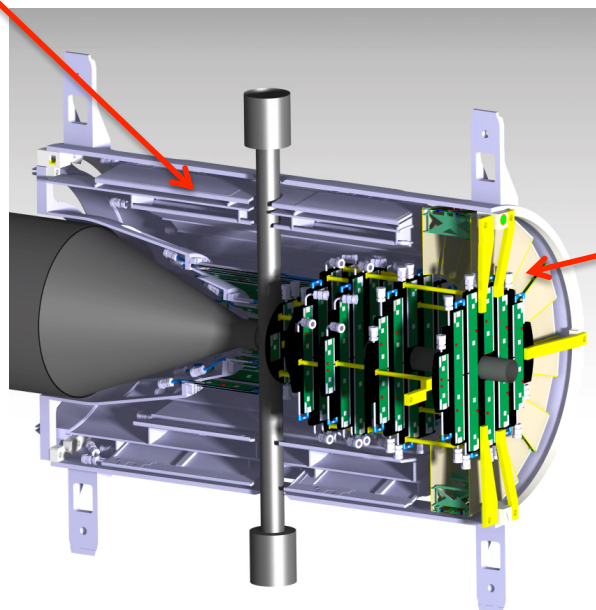
Mechanical Integration – Strips



Barrel part

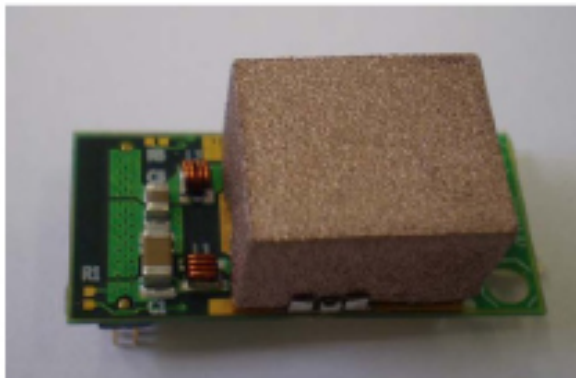
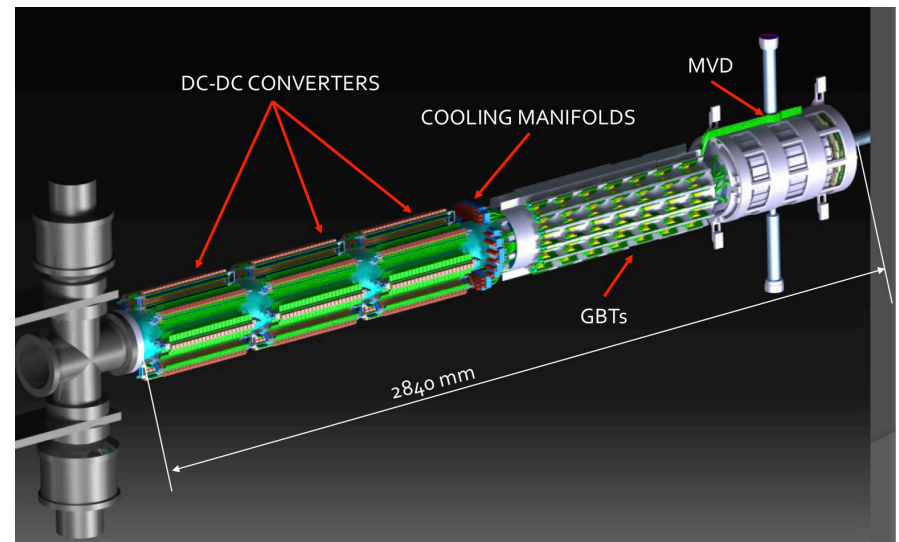


Disk part

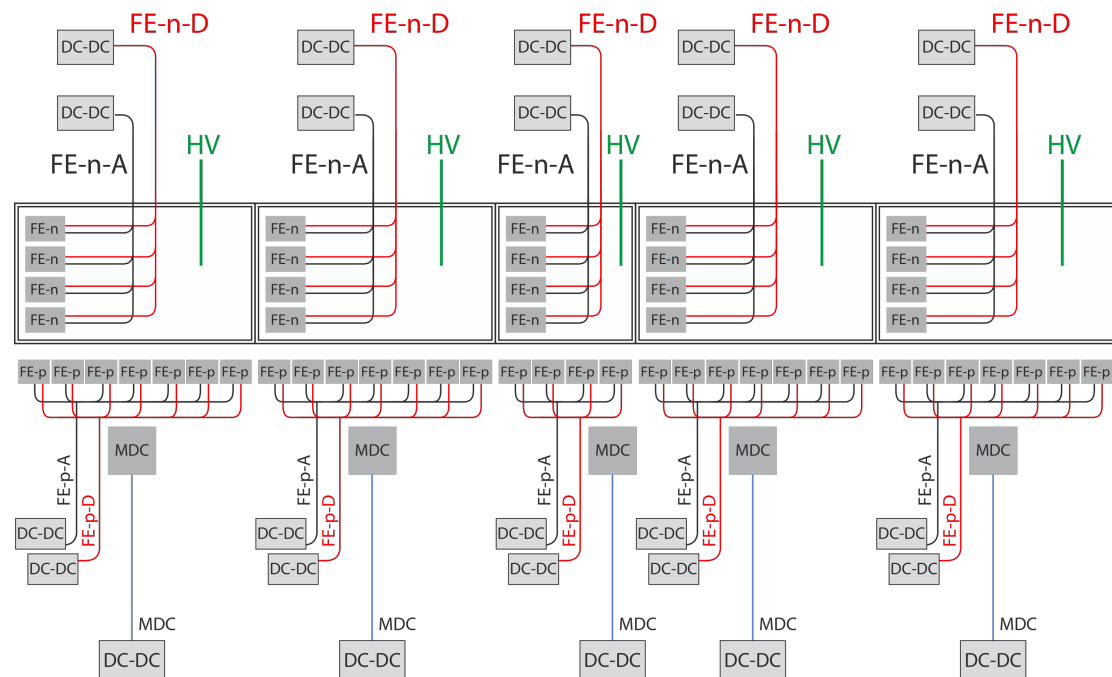


Strip Stave Powering

- DC-DC powering operating in B=2T
- 5 power domains per sensor
- up to 60 power supply cables per strip barrel stave (up to 4 m long)
- ~1500 converters for barrels + disks (+600 for pixel detector)
- MVD services routing is a crucial issue



SM01C converter (CERN development)



Hardware development

Front-end ASIC – I

Requirements to the strip front-end:

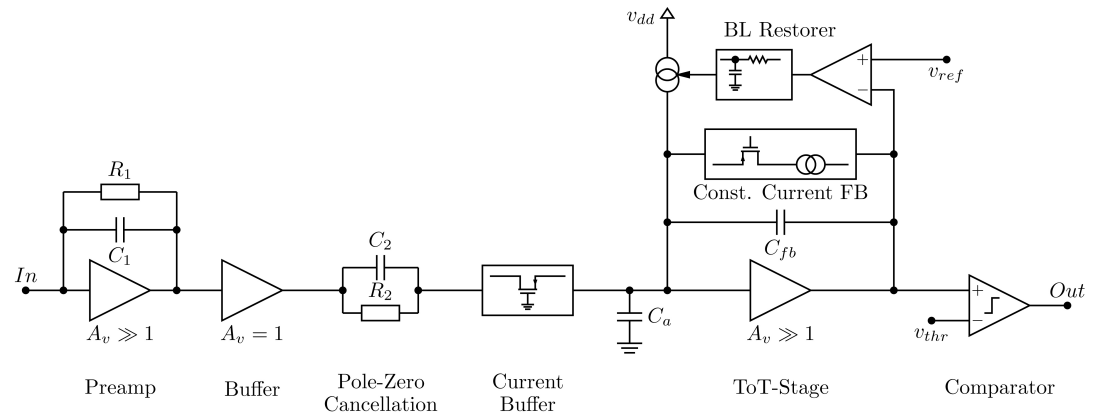
- Self-triggering
- Radiation hard up to 10 Mrad
- Power budget $1\text{W}/\text{cm}^2$
- Charge measurement
- Input rate up to 40 kHz
- Noise $<1500\text{ e}^-$
- Fully digital outputs
- Sensor capacitance at the input $\sim 20\text{ pF}$

→ no chip available on the market which satisfies all these requirements

Front-end ASIC – II

New strip ASIC:

- Developed by INFN Torino with JLU Gießen and FZ Jülich
- Front-end adapted from ToPix (modified for larger input capacitance)
- Amplitude measurement with the Time-over-Threshold technique
- High resolution (~ 100 ps) time digitization with TDCs adapted from TOFPET
- Clock frequency 155.52 MHz
- Power budget: ~ 4 mW / ch



First submission expected in some months

Sensor Characterization – Prototypes

Wafer properties:

- Fabricated at CiS, Germany
- FZ Si, 4" wafer
- Thickness: $285 \pm 10 \mu\text{m}$
- Resistivity: $2.3 \dots 5 \text{ k}\Omega \cdot \text{cm}$
- Biasing: punch-through
- n-side insulation: p-spray

General sensor properties:

- Stereo angle: 90°
- Guard rings: 8
- Pitch: $65 \mu\text{m}$ or $50 \mu\text{m}$
- Readout: 1 DC pad and 4 AC pads per strip

S1 (PANDA rectangular)

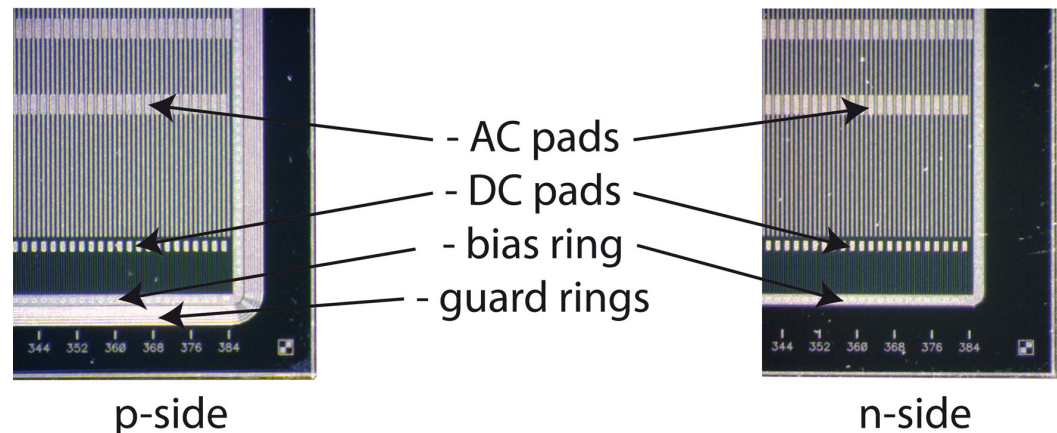
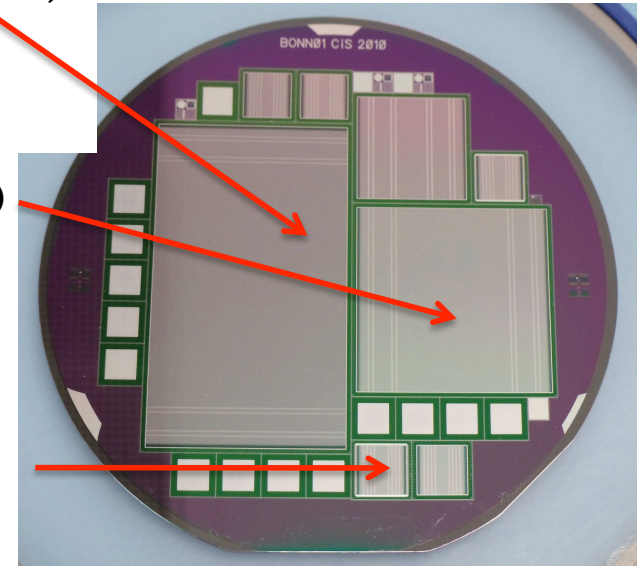
- 896×512 channels
- $58.3 \times 33.3 \text{ mm}^2$

S2 (PANDA squared)

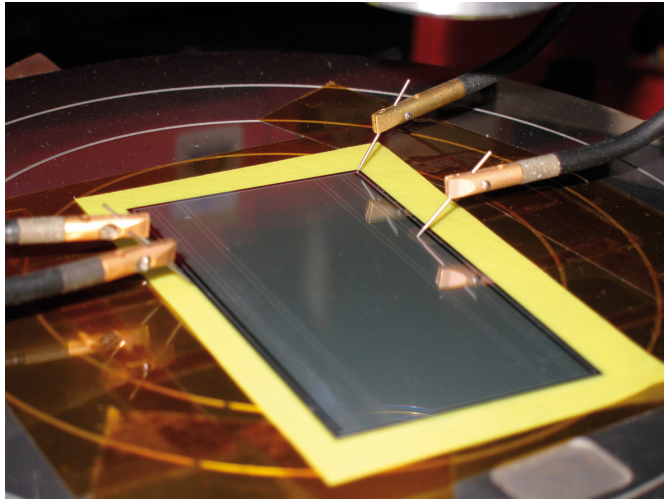
- 512×512 channels
- $33.3 \times 33.3 \text{ mm}^2$

S4 ("Baby")

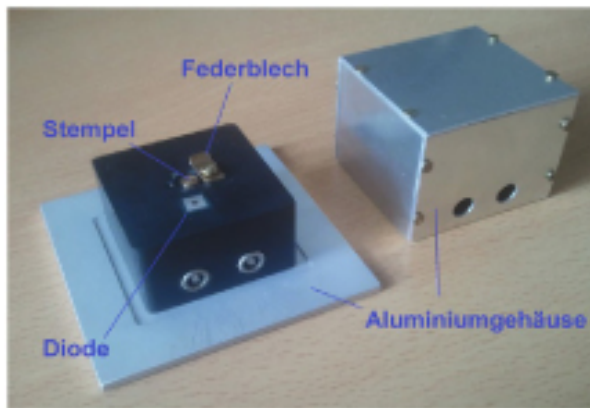
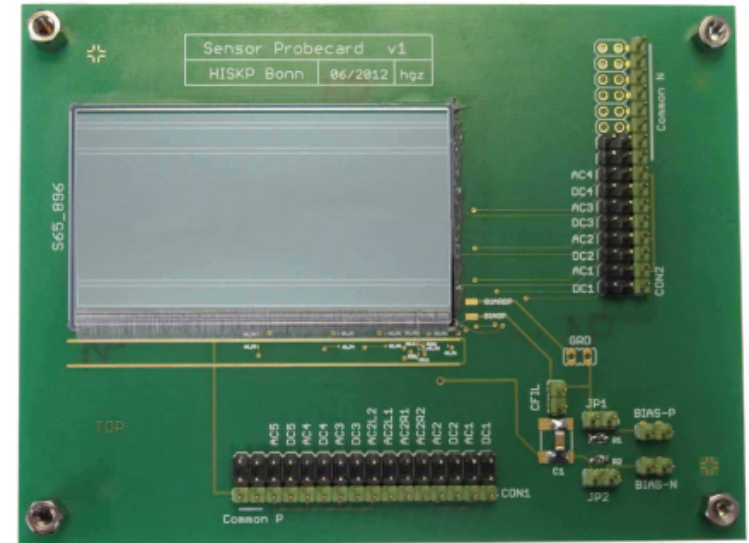
- 128×128 channels
- $8.4 \times 8.4 \text{ mm}^2$



Sensor Characterization – Setup

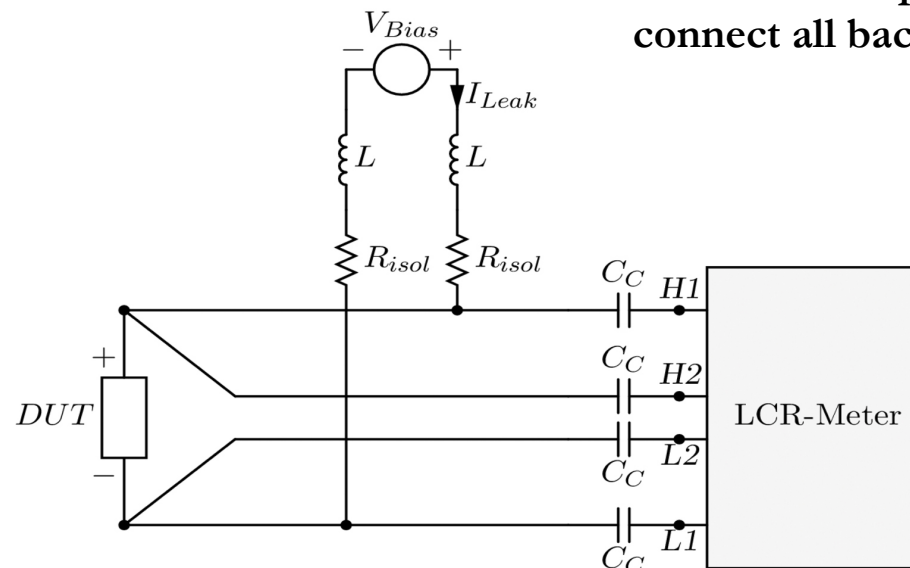


Probe station

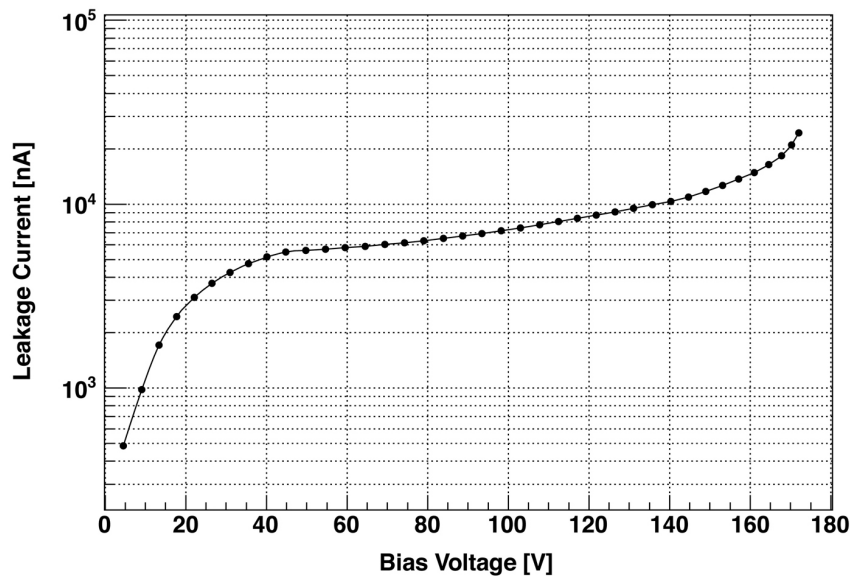


Test enclosure for connection of diodes

Fixed contact probe-card to connect all back-side strips

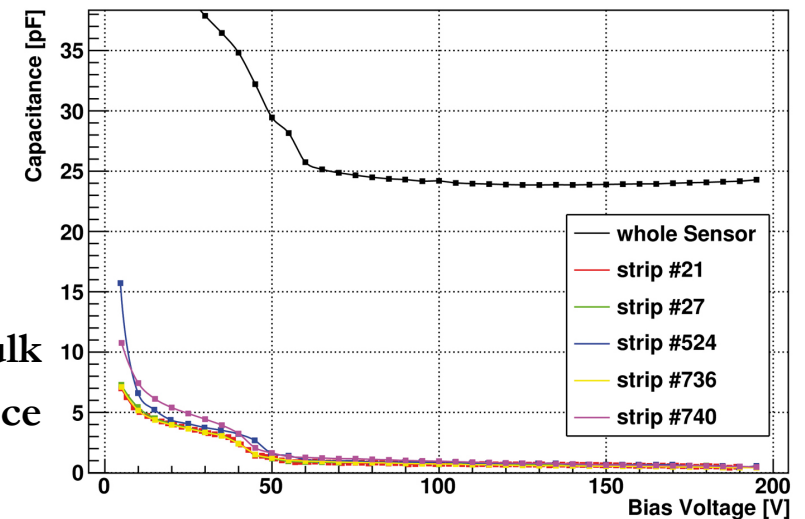


Sensor Characterization – S1 Sensor

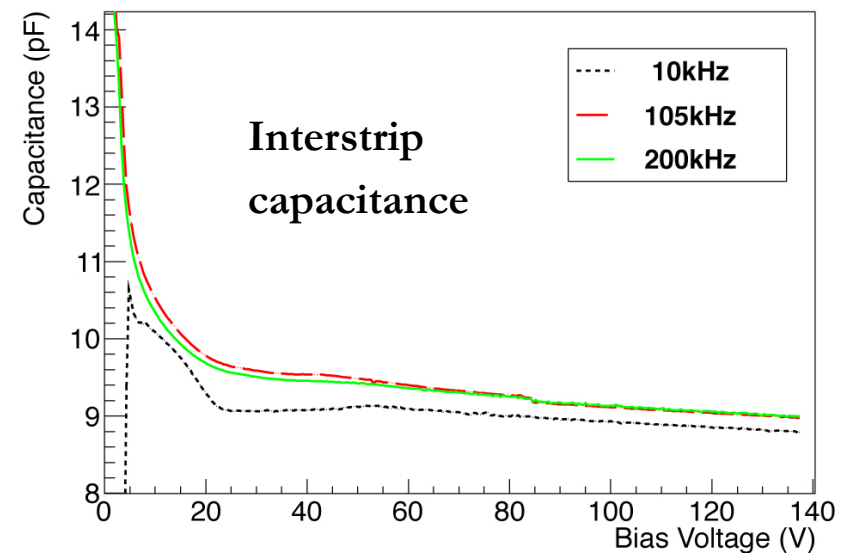


Leakage current

Strip-to-bulk capacitance



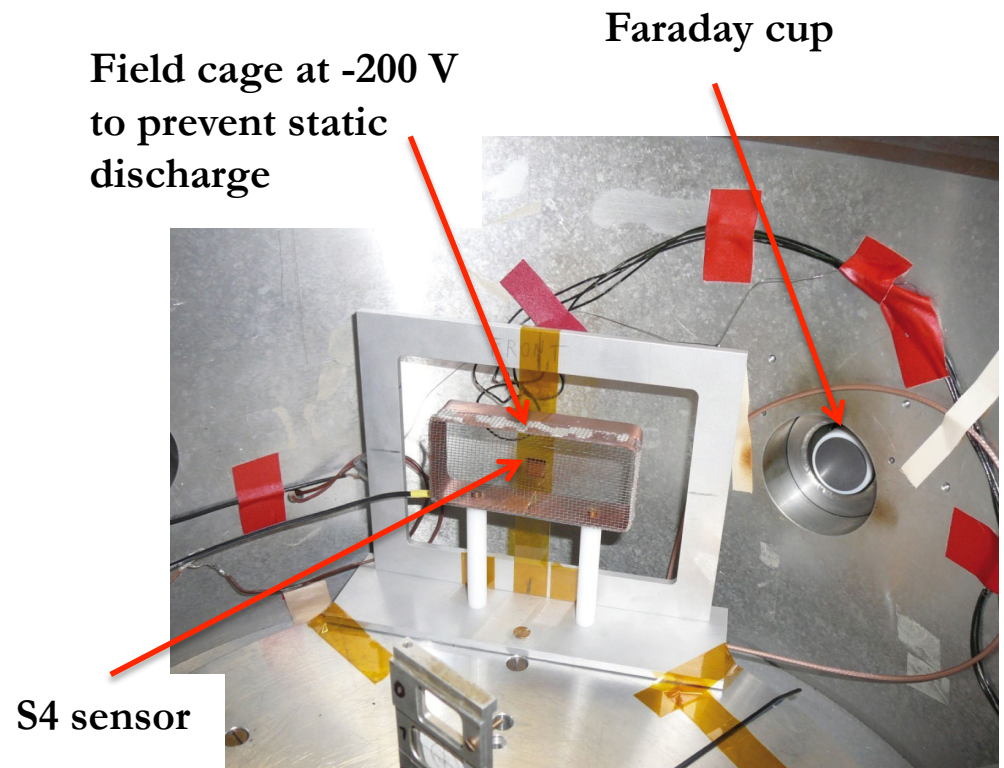
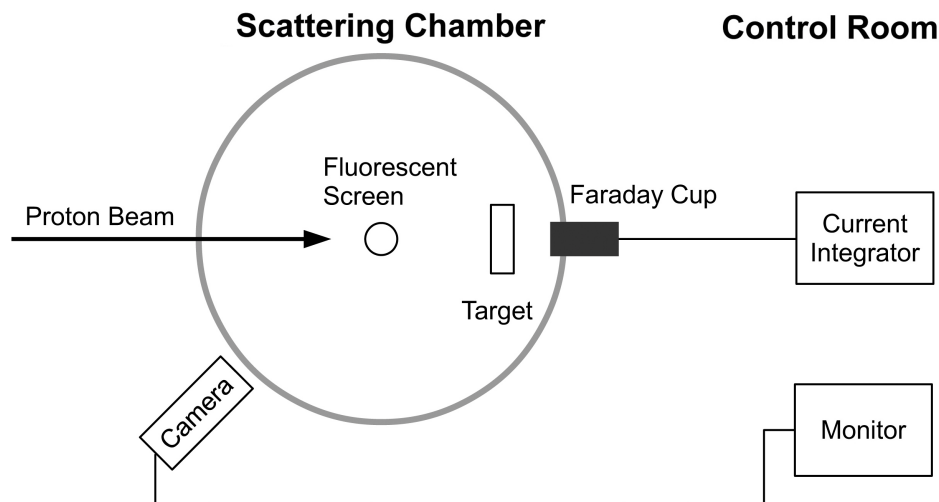
Parameter	Measurement
Full depletion voltage	~ 55 V
Leakage current	~ 6 μ A @ 50 V
Bulk capacitance	680 pF
Interstrip capacitance	~ 10 pF @ 50 V
Coupling capacitance	> 45 pF/cm
C_{input}	9.8 \pm 0.2 pF (p-side) 17.1 \pm 0.4 pF (n-side)



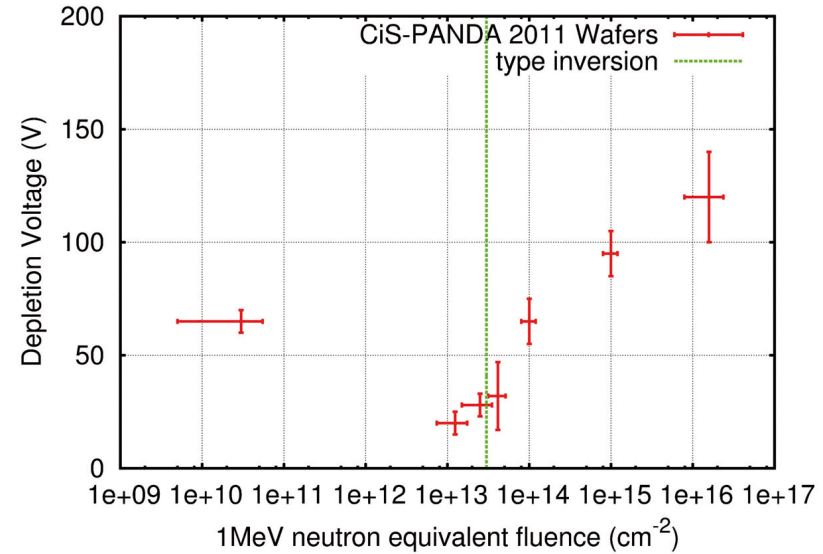
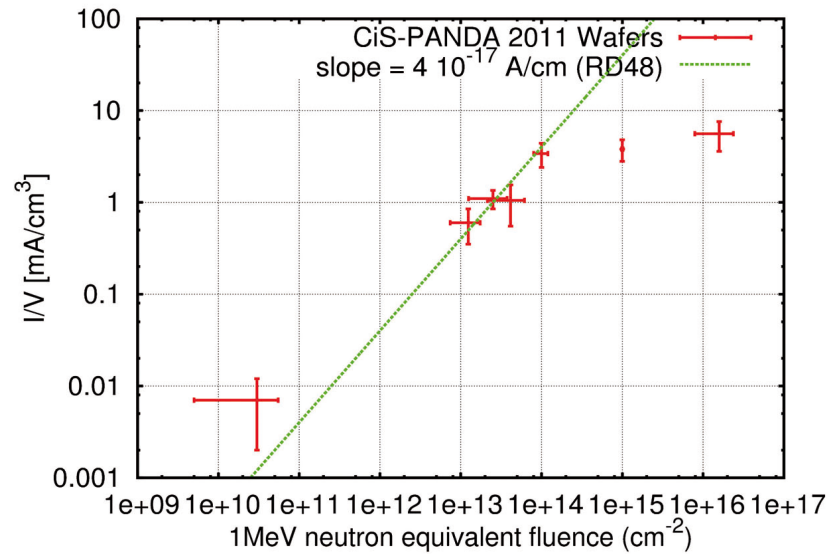
Sensor Irradiations – I

Irradiation studies on S4 (“Baby”) sensors

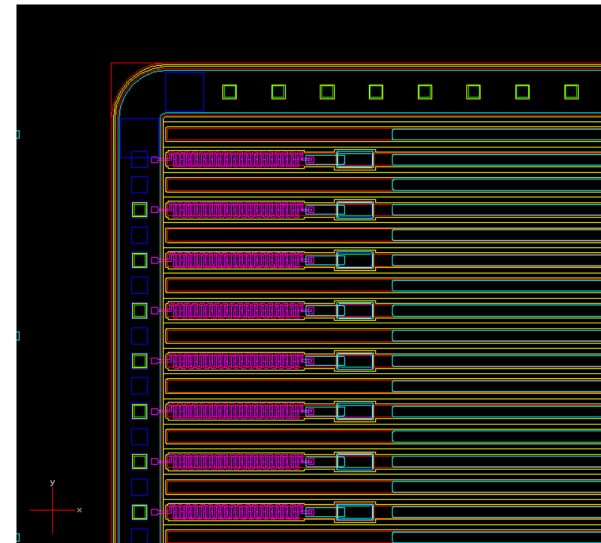
- Proton irradiations at the Bonn Isochronous Cyclotron
→ fluence between 10^{13} and 10^{15} n 1MeV eq /cm²
- Neutron low-fluence ($3 \cdot 10^{10}$ n 1MeV eq /cm²) irradiation with Am-Be source
- Neutron high-fluence ($1.6 \cdot 10^{16}$ n 1MeV eq /cm²) irradiation at research reactor in Delft
- Annealing phase (80 minutes at 60°C)



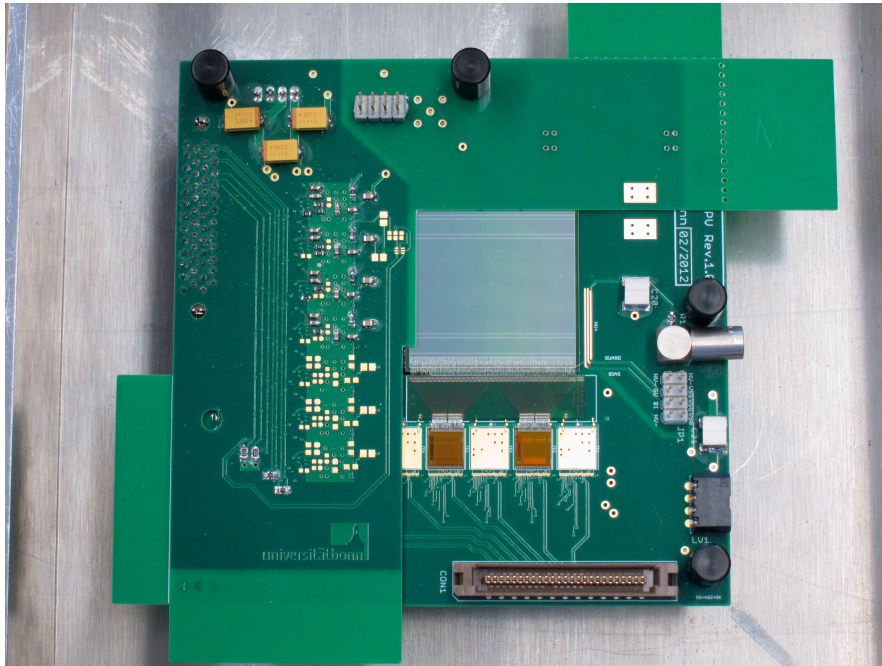
Sensor Irradiations – II



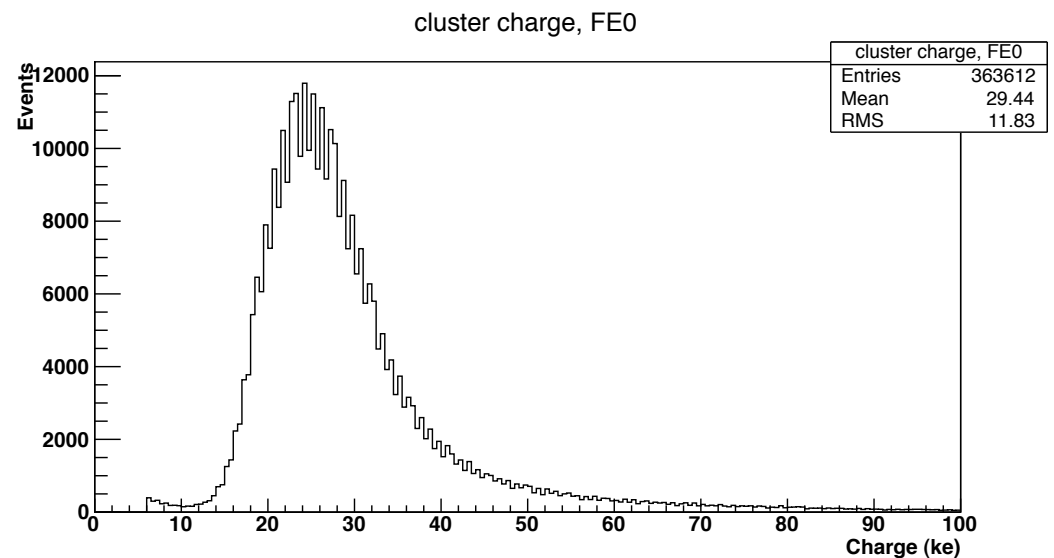
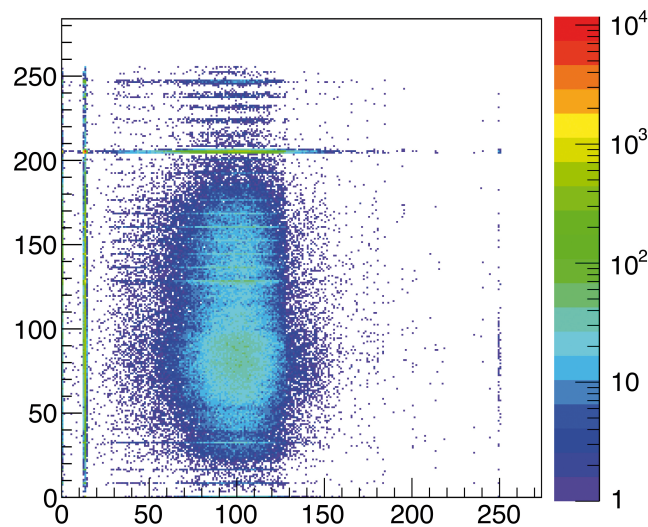
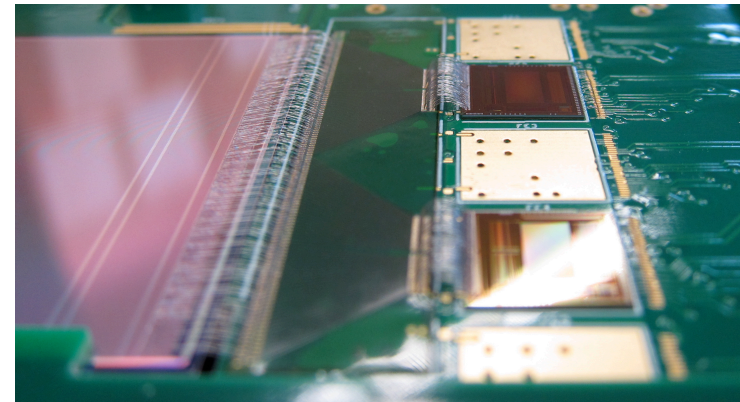
- Full depletion voltage remains below 100 V at end of PANDA lifetime
- New sensor batch with polysilicon biasing is coming soon



Sensor Characterization – Beam Test

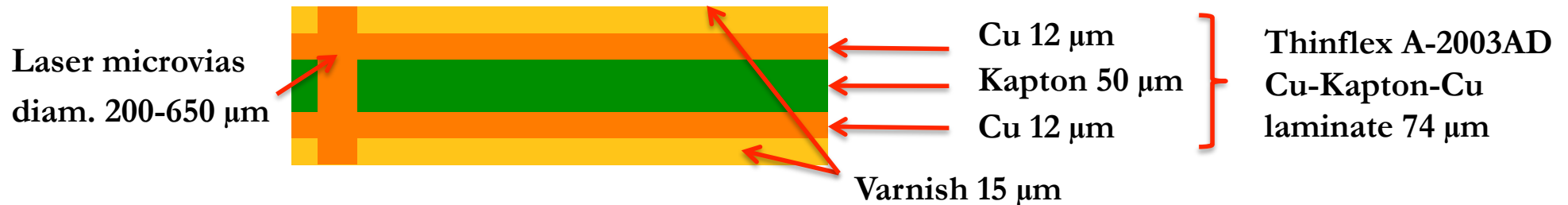


Squared sensor assembled on a test board and successfully tested at SPS, CERN (September 2012)

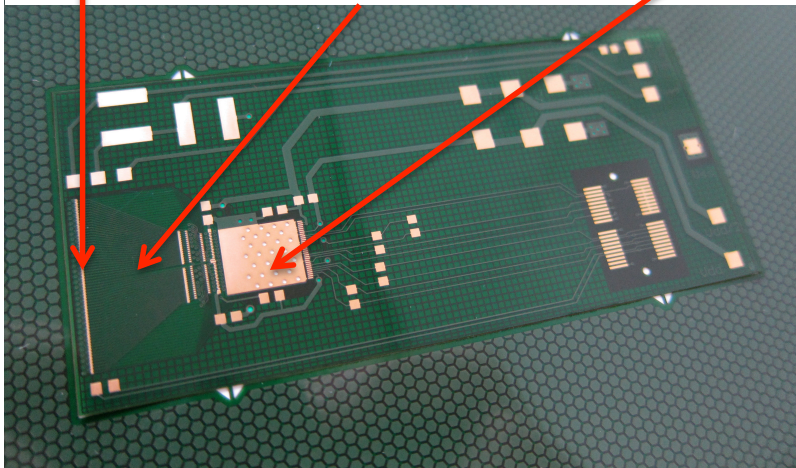


Strip Barrels – Hybrid Bus

- Connects the sensor and the front-end chips, adapting the pitch
- Distributes I/O signals (and possibly power) to the chips
- Reduced-scale prototype with APV25 readout chip produced



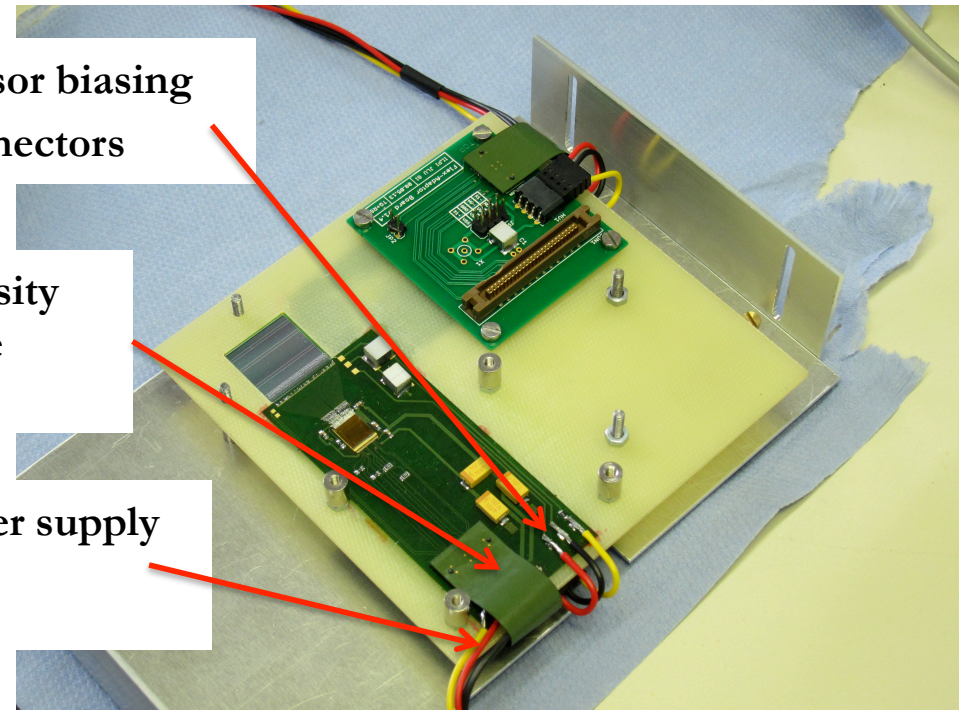
Bonding pads for the sensor
Pitch adapter
Pad for 1 APV readout chip



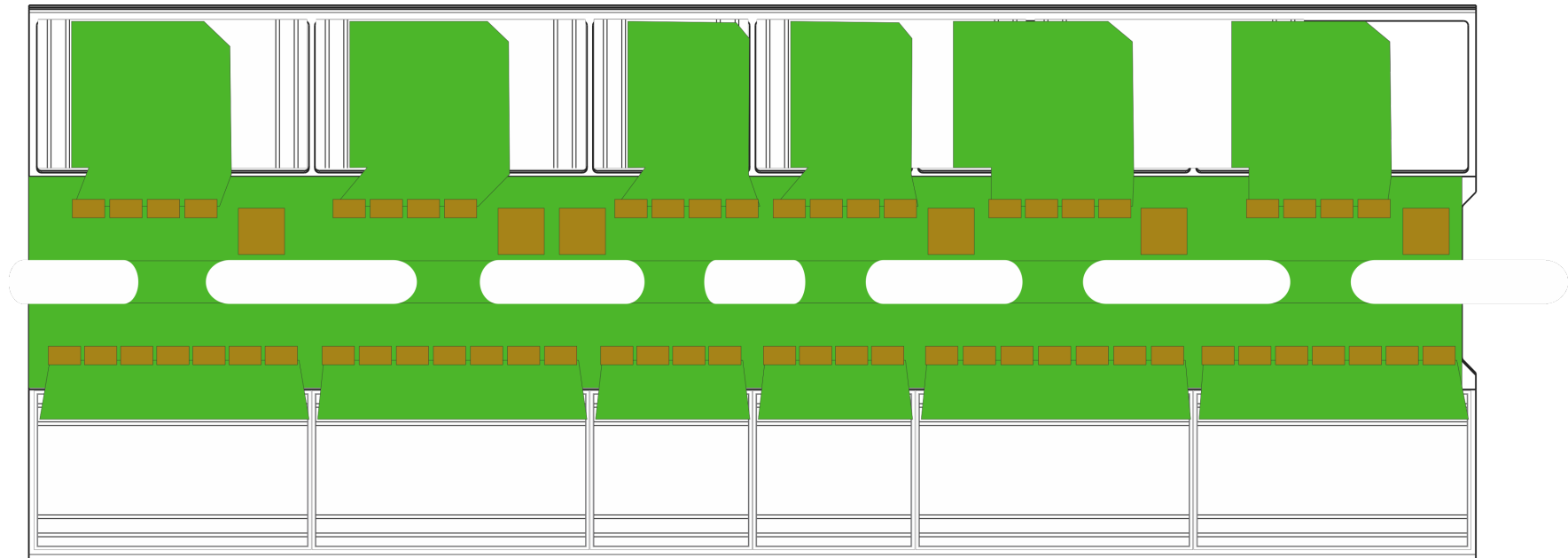
Sensor biasing connectors

High density data cable

APV power supply connector

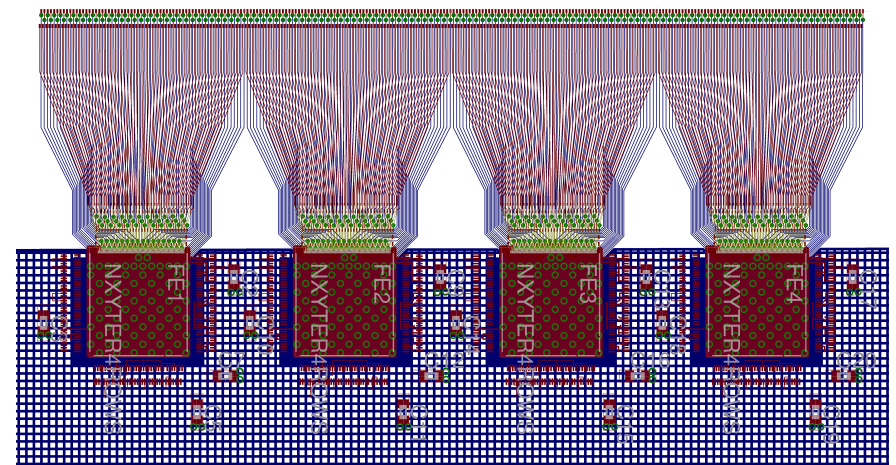
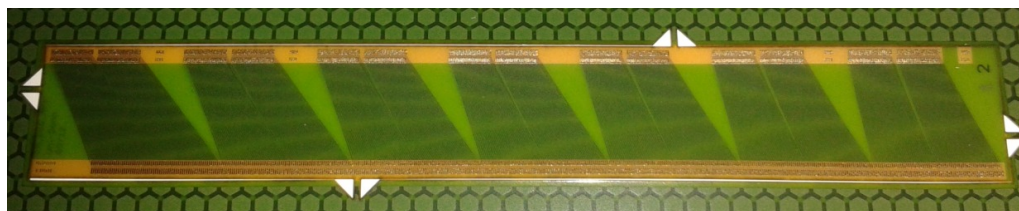


Strip Barrels – Hybrid Bus II



Proposal for the full hybrid layout

Chips-sensor
fanout structure



Conclusions and Outlook

- **The general design of the PANDA MVD is finalized.**
- **Development and validation of components is ongoing:**
 - Front-end electronics under design;
 - First batch of sensors fully characterized;
 - Reduced-scale hybrid produced and under test.
- **Some future steps:**
 - Development of the readout chip;
 - Characterization of the new sensor technology;
 - Design and test of a full-scale hybrid;
 - Validation of the stave cooling system.



Thank you for your attention!

GEFÖRDERT VOM



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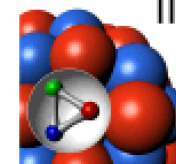
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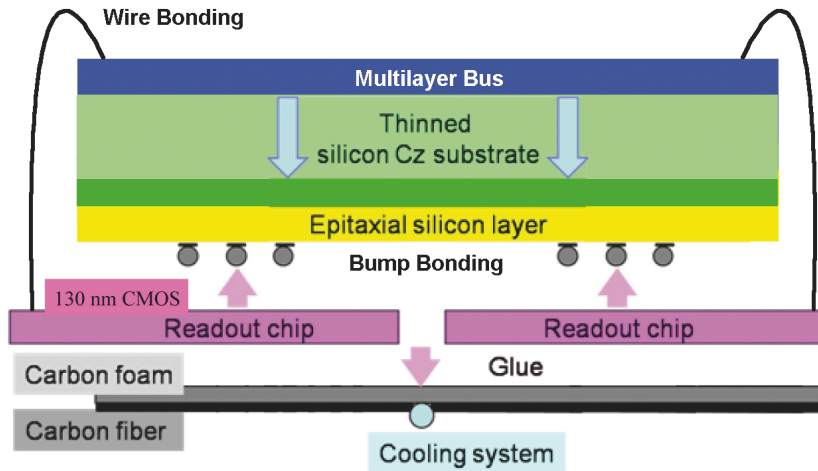
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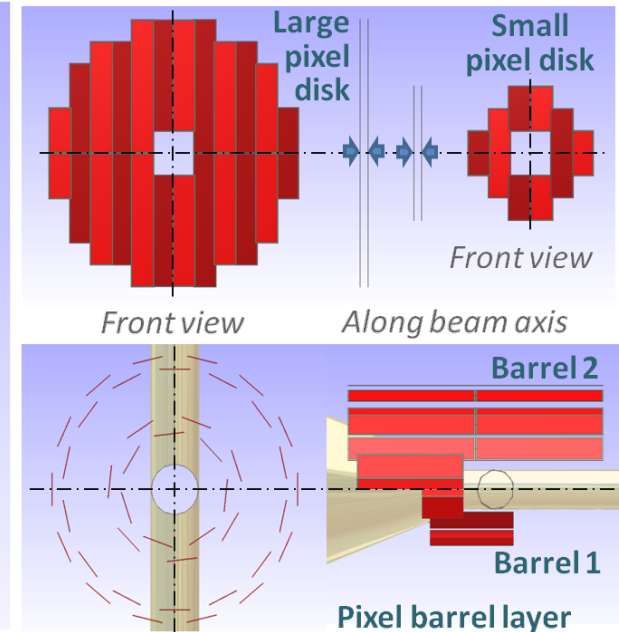
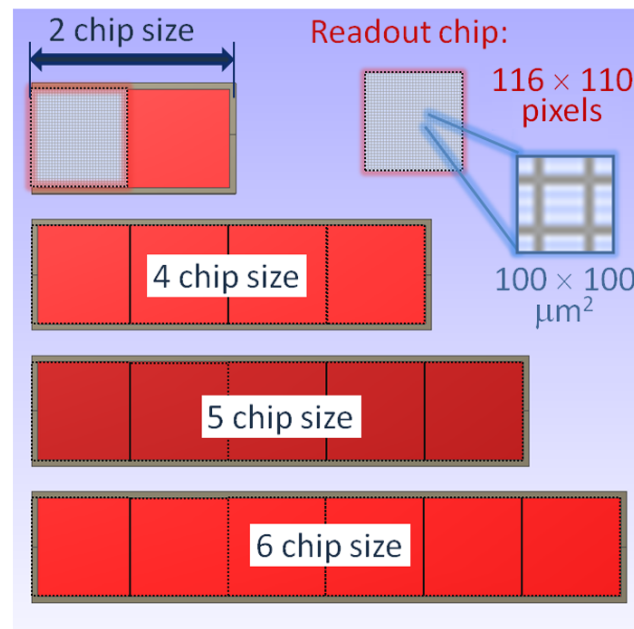
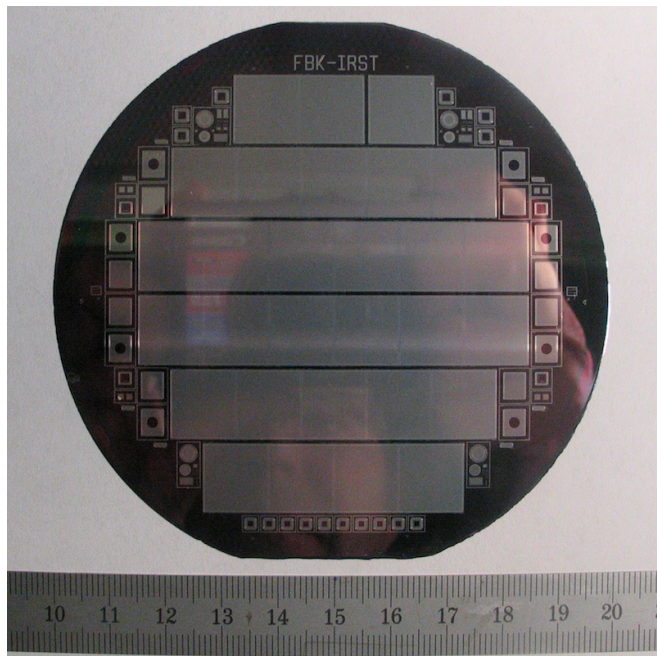
Backup slides

Pixel Detectors

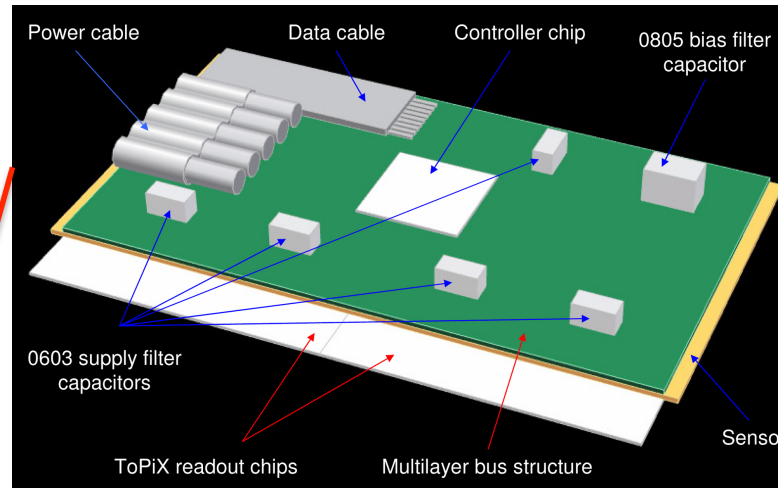


Sandwich structure:

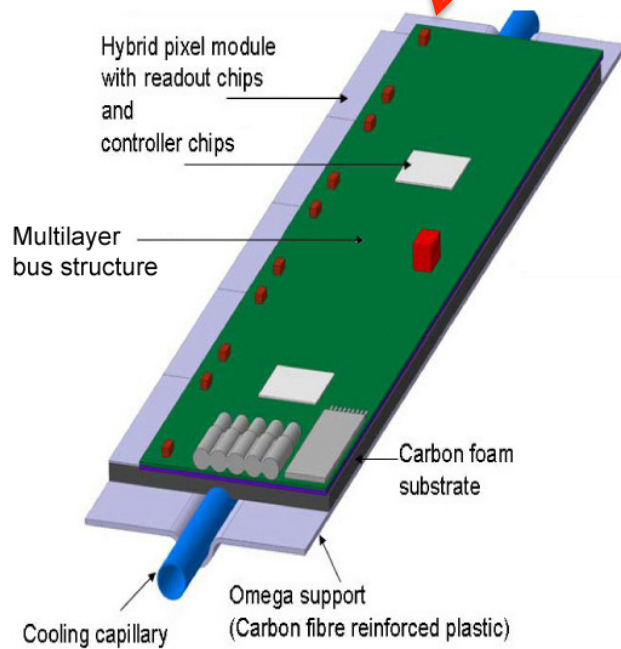
- Bus
- Sensor
- Read-out chips
- Mechanical support with embedded cooling



Pixel Detectors – II



Linear barrel
stave



Half disk

